



SOT2039-2(SC)

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

22 November 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HWQFN32
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-10-2021
Manufacturer package code	98ASA01733D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	5	-	mm
package width	-	5	-	mm
package height	-	0.68	0.75	mm
nominal pitch	-	0.5	-	mm



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2 Package outline

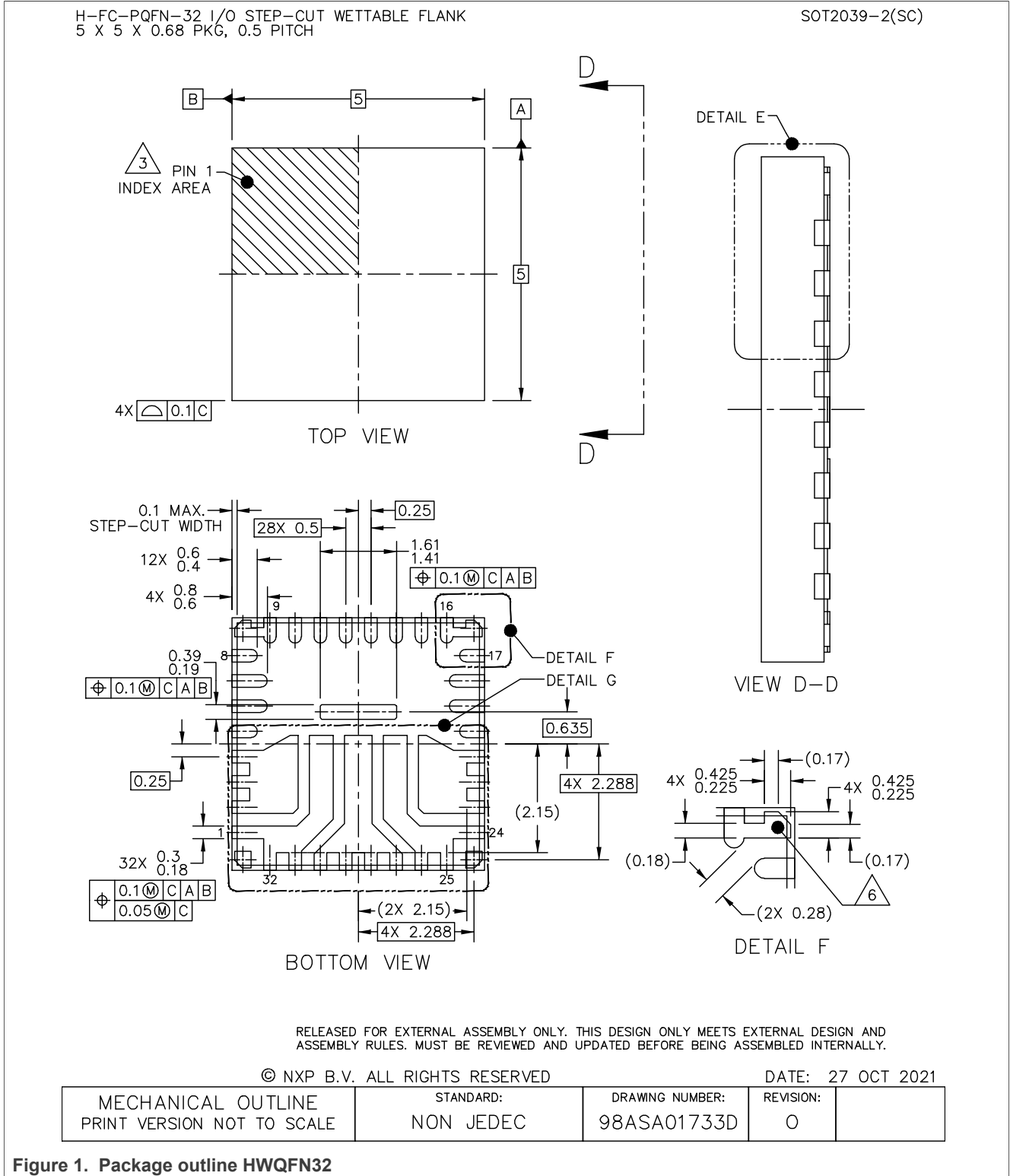


Figure 1. Package outline HWQFN32

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

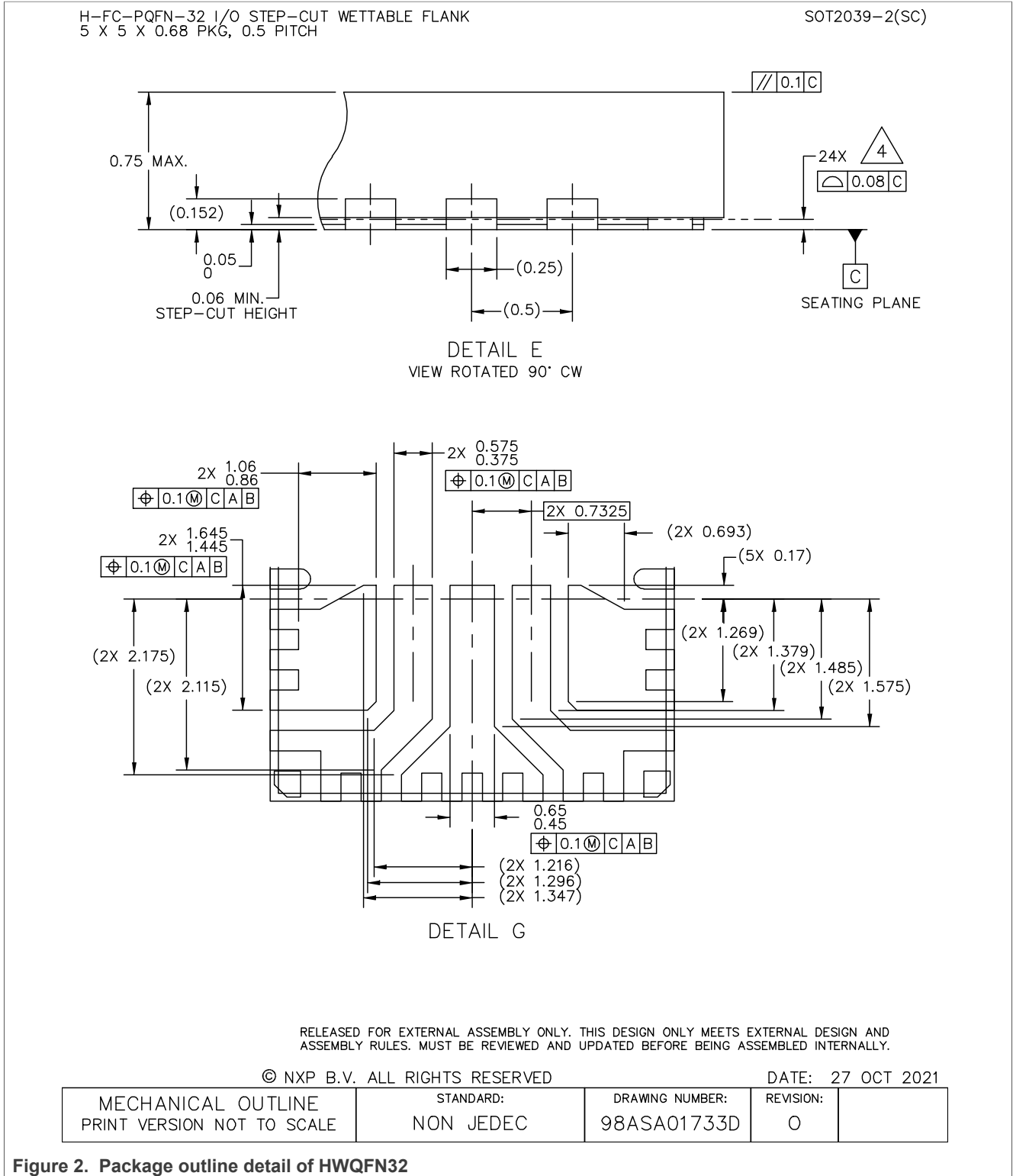
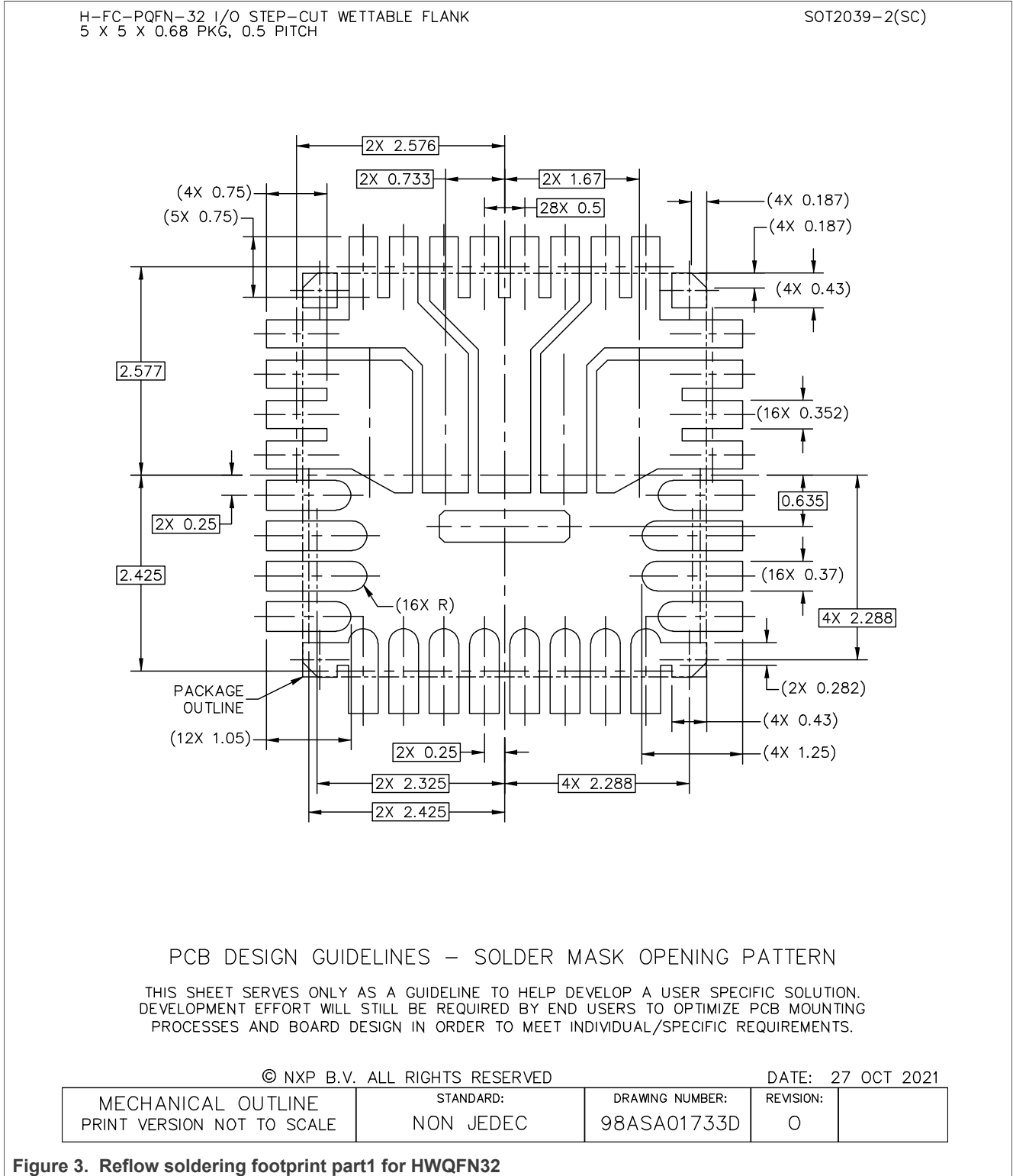


Figure 2. Package outline detail of HWQFN32

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

3 Soldering



HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

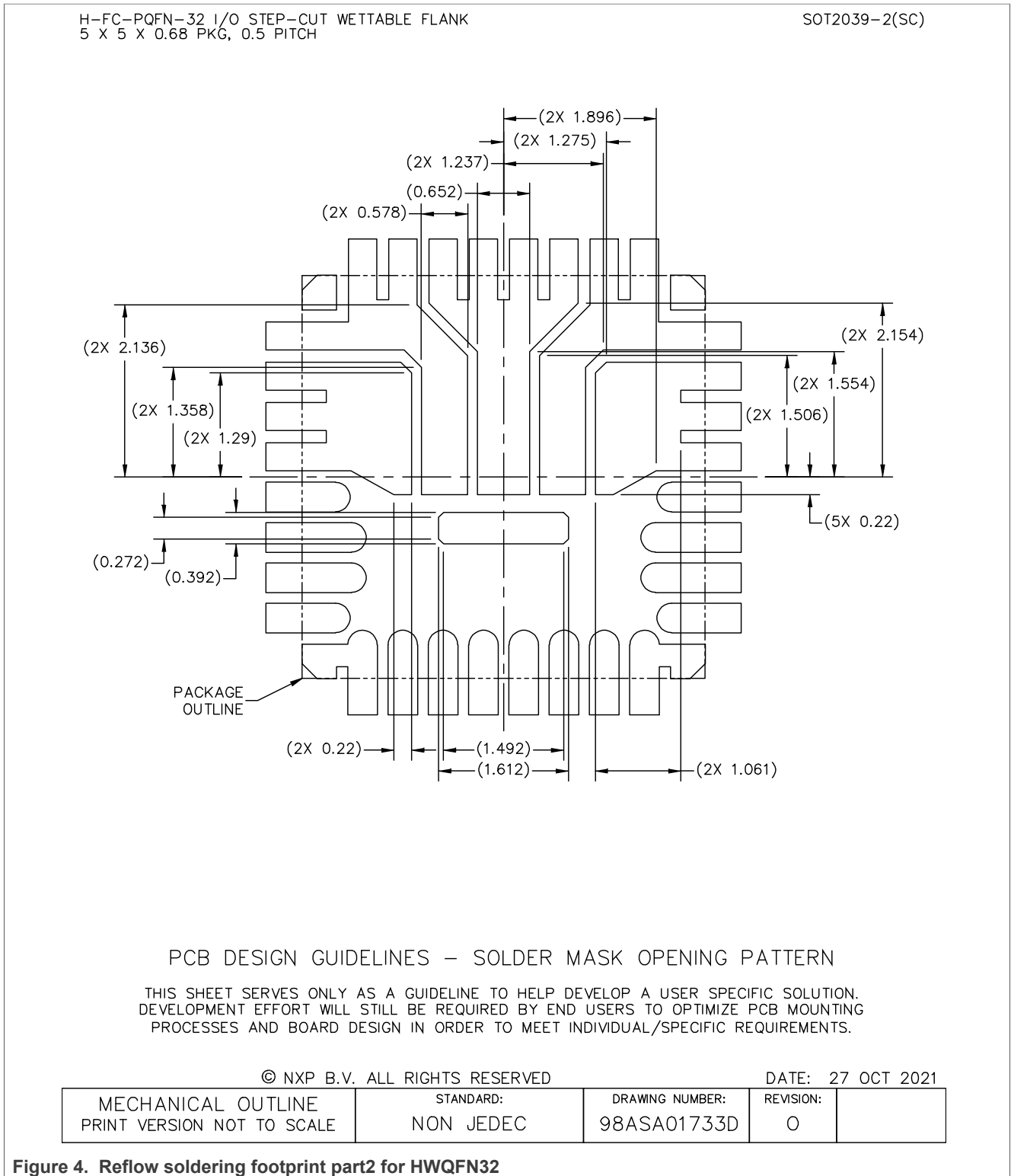
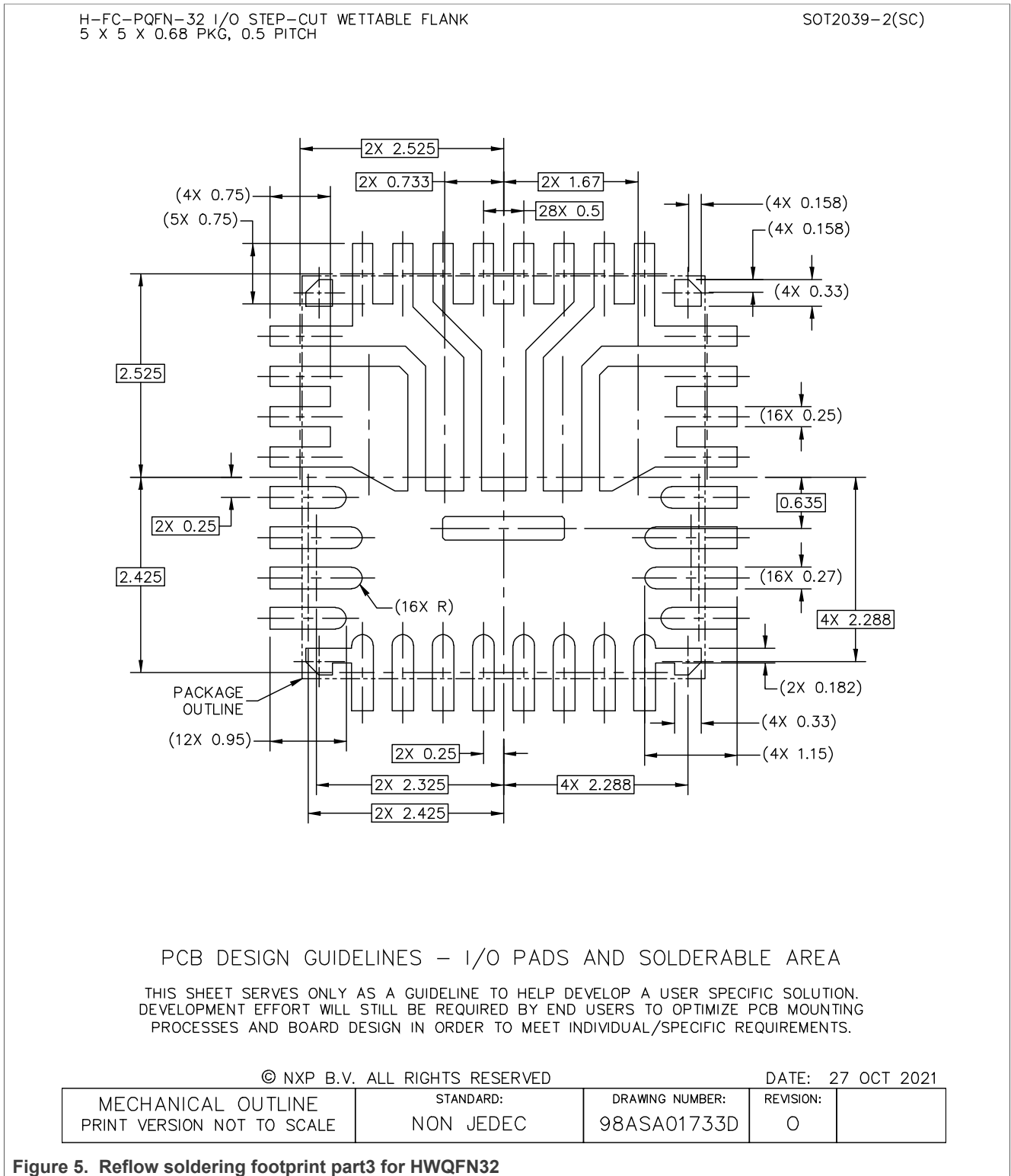
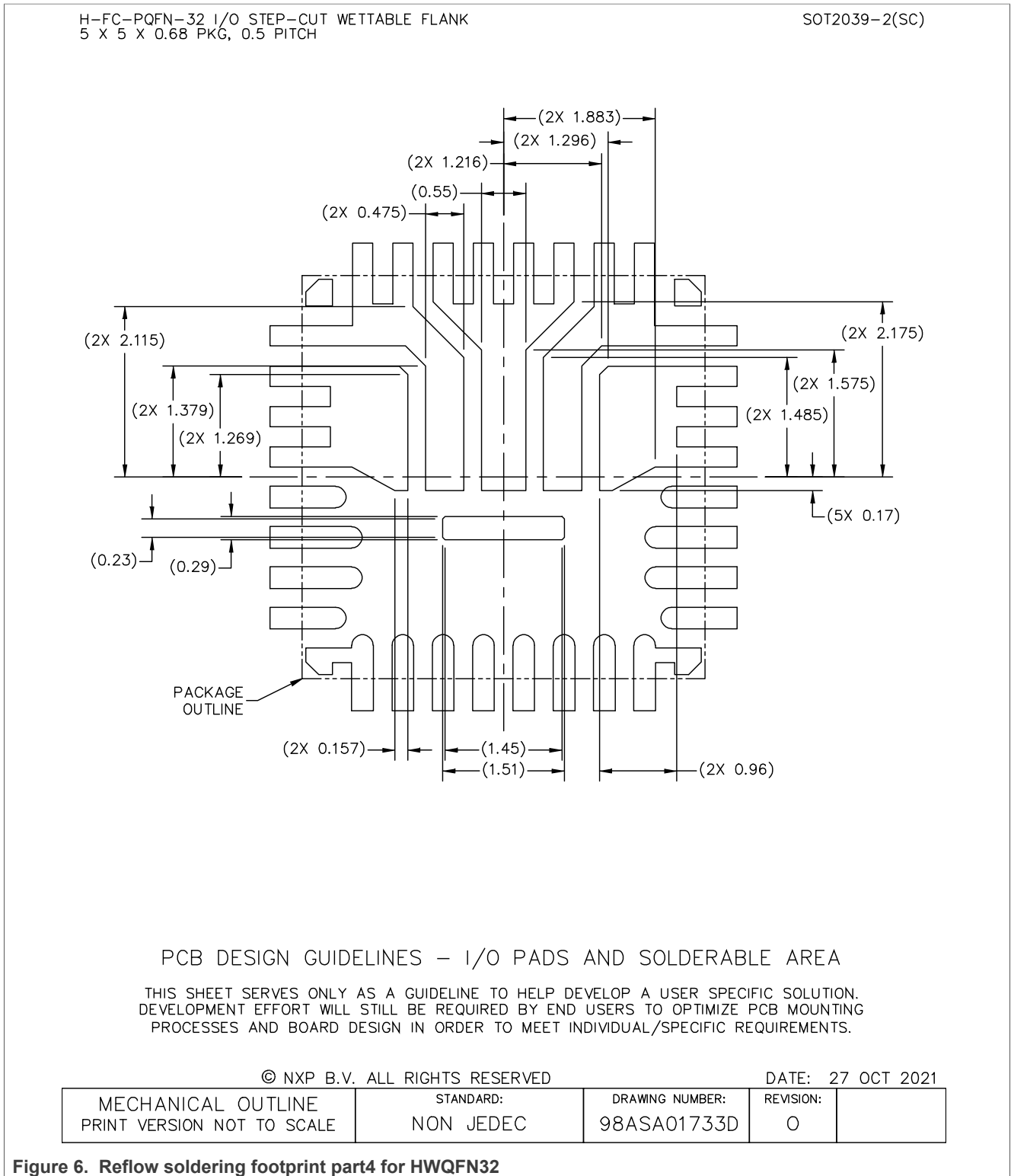


Figure 4. Reflow soldering footprint part2 for HWQFN32

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body



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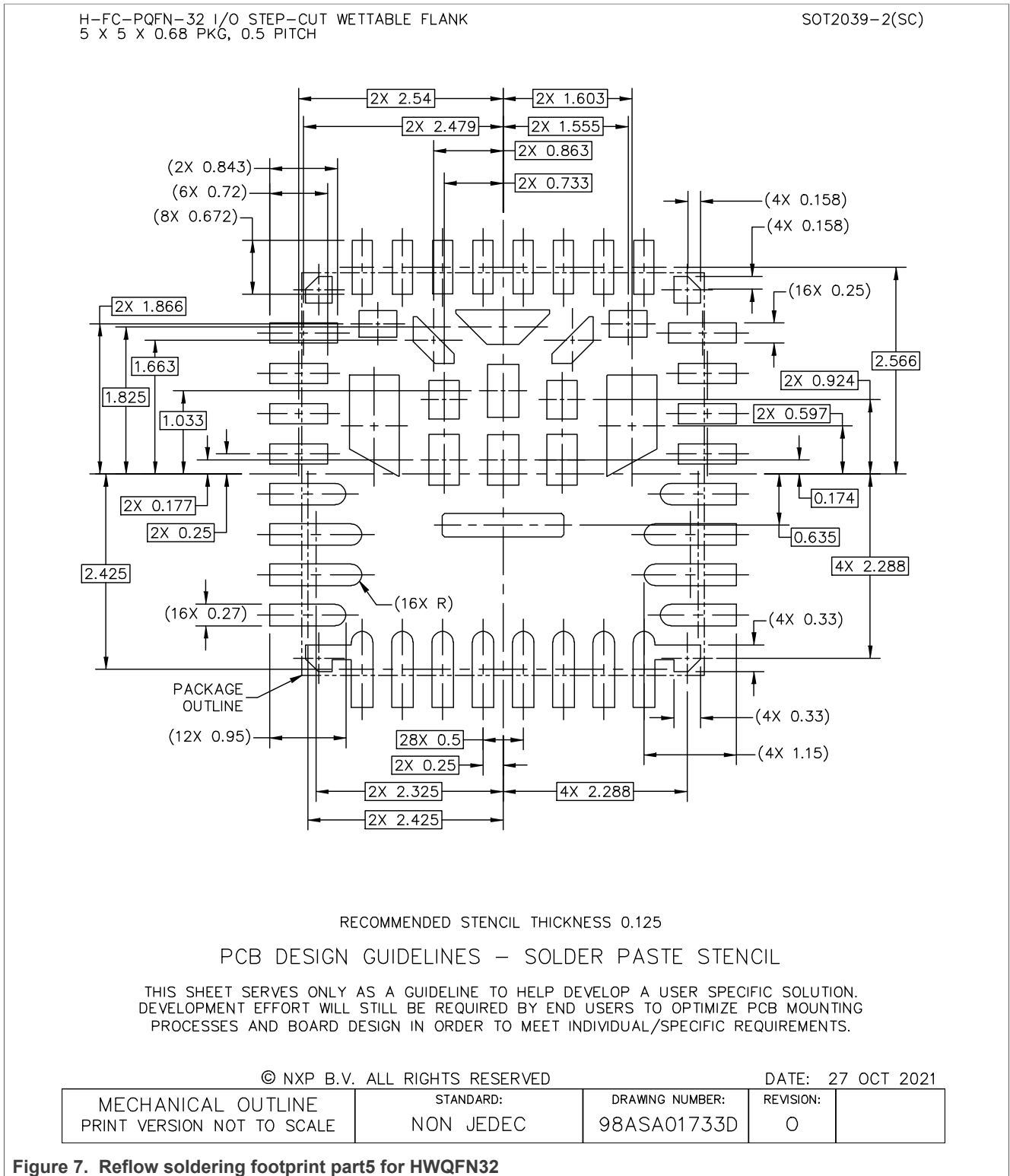
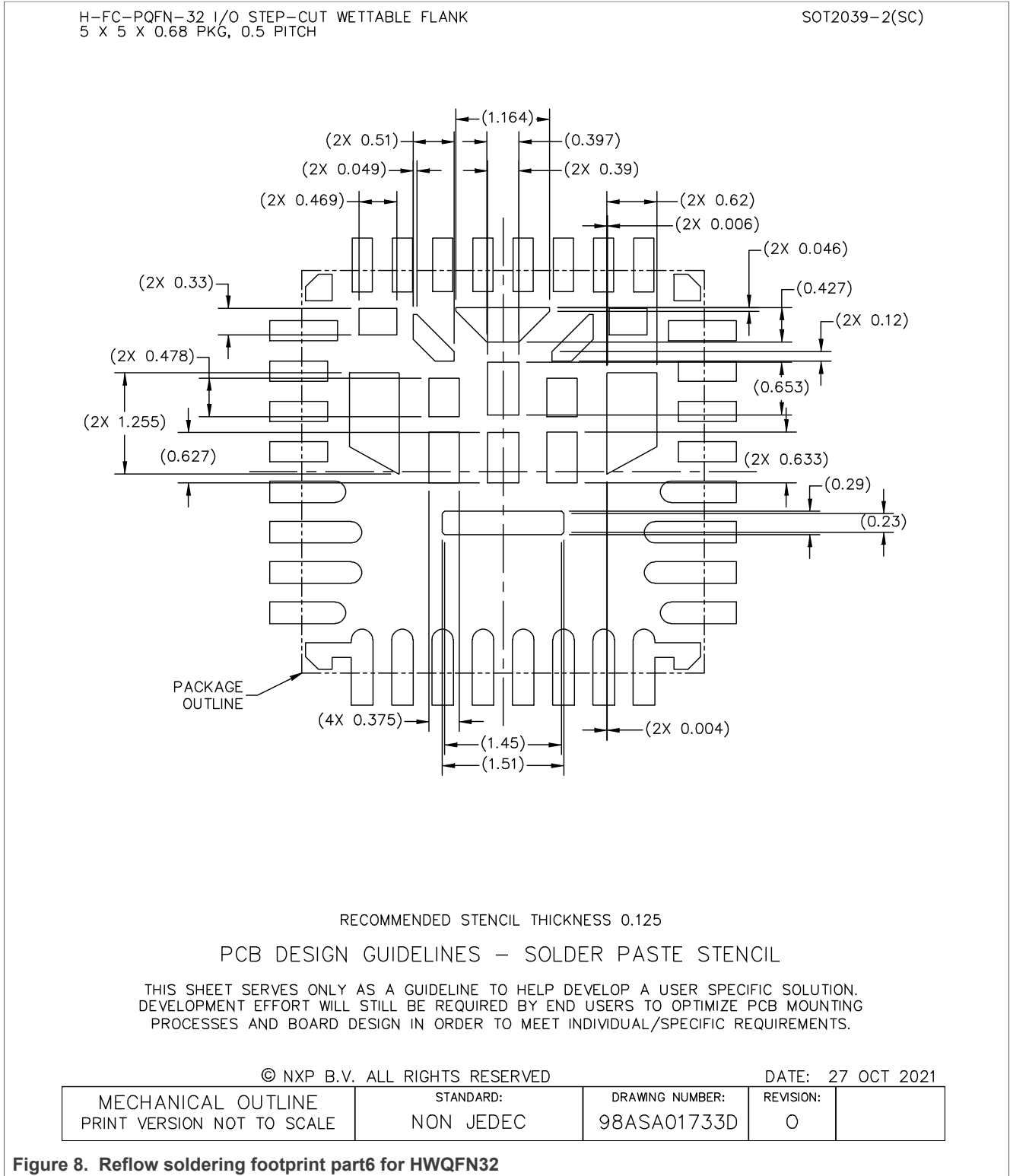


Figure 7. Reflow soldering footprint part5 for HWQFN32

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body



HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

H-FC-PQFN-32 I/O STEP-CUT WETTABLE FLANK
5 X 5 X 0.68 PKG, 0.5 PITCH

SOT2039-2(SC)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE, SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. ANCHORING PADS.

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DATE: 27 OCT 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01733D	REVISION: 0	
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Figure 9. Package outline note HWQFN32

HWQFN32, thermal enhanced, very-very thin quad flat package, no leads, step-cut wettable flank, 0.5 mm pitch, 5 mm x 5 mm x 0.68 mm body

4 Legal information

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